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(12) **United States Design Patent** (10) **Patent No.: US D864,885 S**

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(54) **INFRARED LAMP HEATER TRANSMISSION WINDOW FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

(71) Applicant: **Hitachi High-Technologies Corporation**, Minato-ku, Tokyo (JP)

(72) Inventors: **Michiaki Kobayashi**, Tokyo (JP); **Kazuyuki Hirozane**, Tokyo (JP); **Akio Harada**, Tokyo (JP); **Nobuhide Nunomura**, Tokyo (JP); **Yutaka Kouzuma**, Tokyo (JP)

(73) Assignee: **Hitachi High-Technologies Corporation**, Tokyo (JP)

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184**; D26/138

(58) **Field of Classification Search**
USPC D13/184; D26/1, 24, 74, 72, 36, 59, 118, D26/133, 134
CPC H01R 5/00; H01R 13/46; H01R 13/514; H01R 31/02; F21V 5/00; H01J 19/54; H01J 5/48; H01J 1/02; H01J 5/16; H01J 5/00; H01J 5/50; H01L 33/642; H01L 33/643; H01L 33/644
See application file for complete search history.

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Primary Examiner — Janice Hallmark
Assistant Examiner — Harold E Blackwell, II
(74) *Attorney, Agent, or Firm* — Crowell & Moring LLP

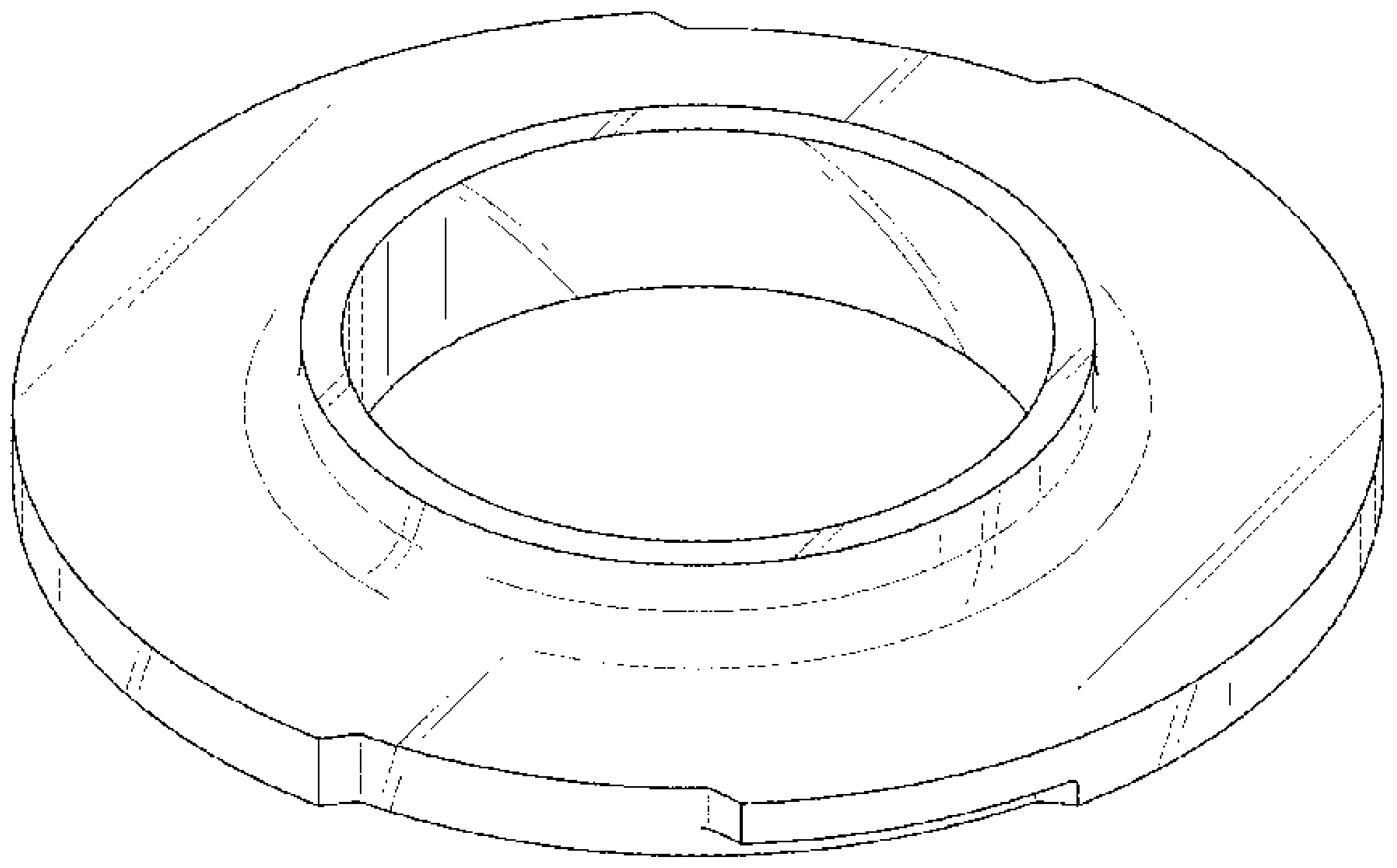
(57) **CLAIM**

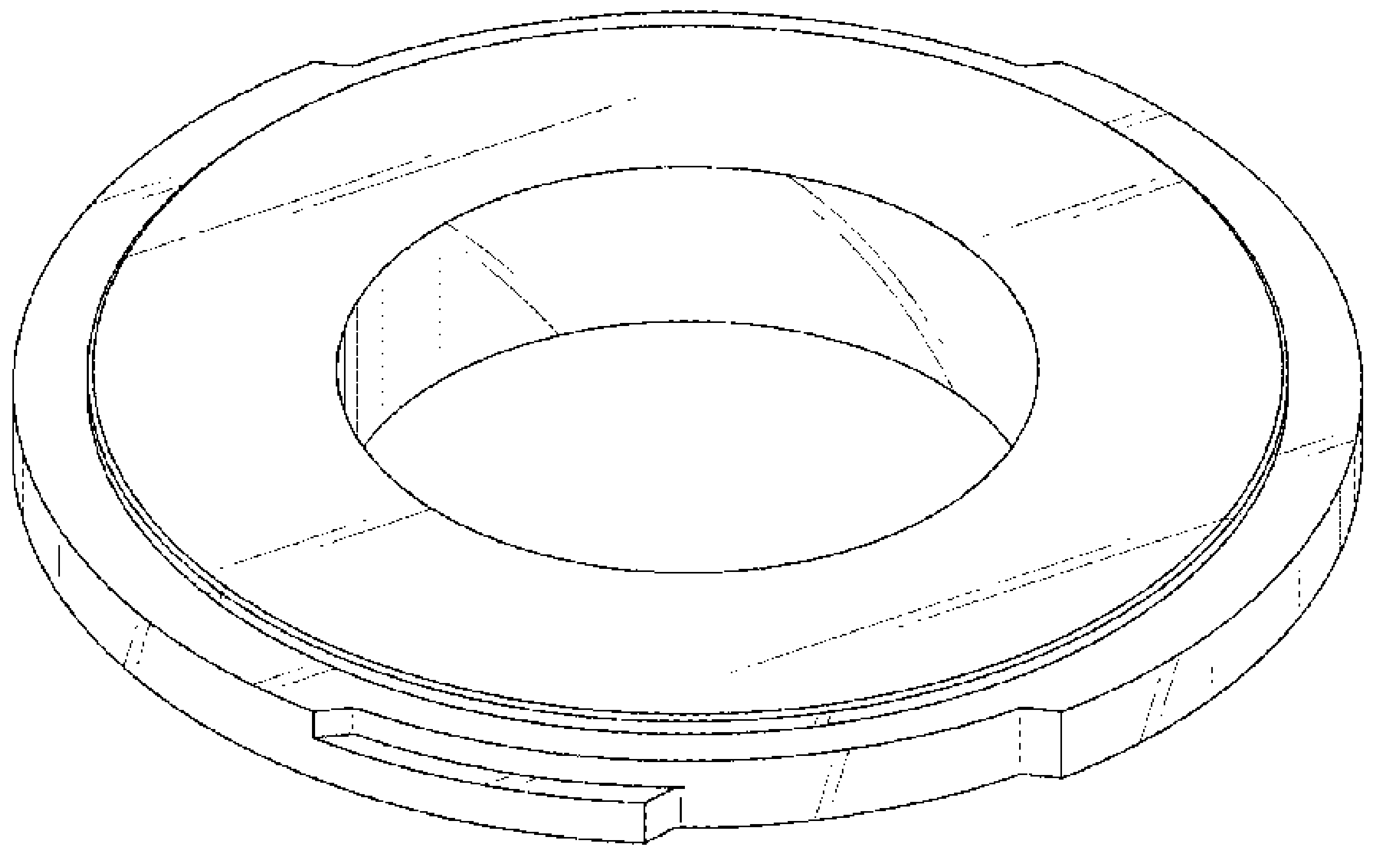
The ornamental design for an infrared lamp heater transmission window for semiconductor manufacturing apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and right side perspective view of an infrared lamp heater transmission window for semiconductor manufacturing apparatus according to the design;
FIG. **2** is a rear, bottom and left side perspective view thereof;
FIG. **3** is a front elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof;
FIG. **8** is a rear elevational view thereof;
FIG. **9** is an end view taken along line **9-9** of FIG. **3**; and,
FIG. **10** is an end view taken along line **10-10** of FIG. **8**.

1 Claim, 5 Drawing Sheets





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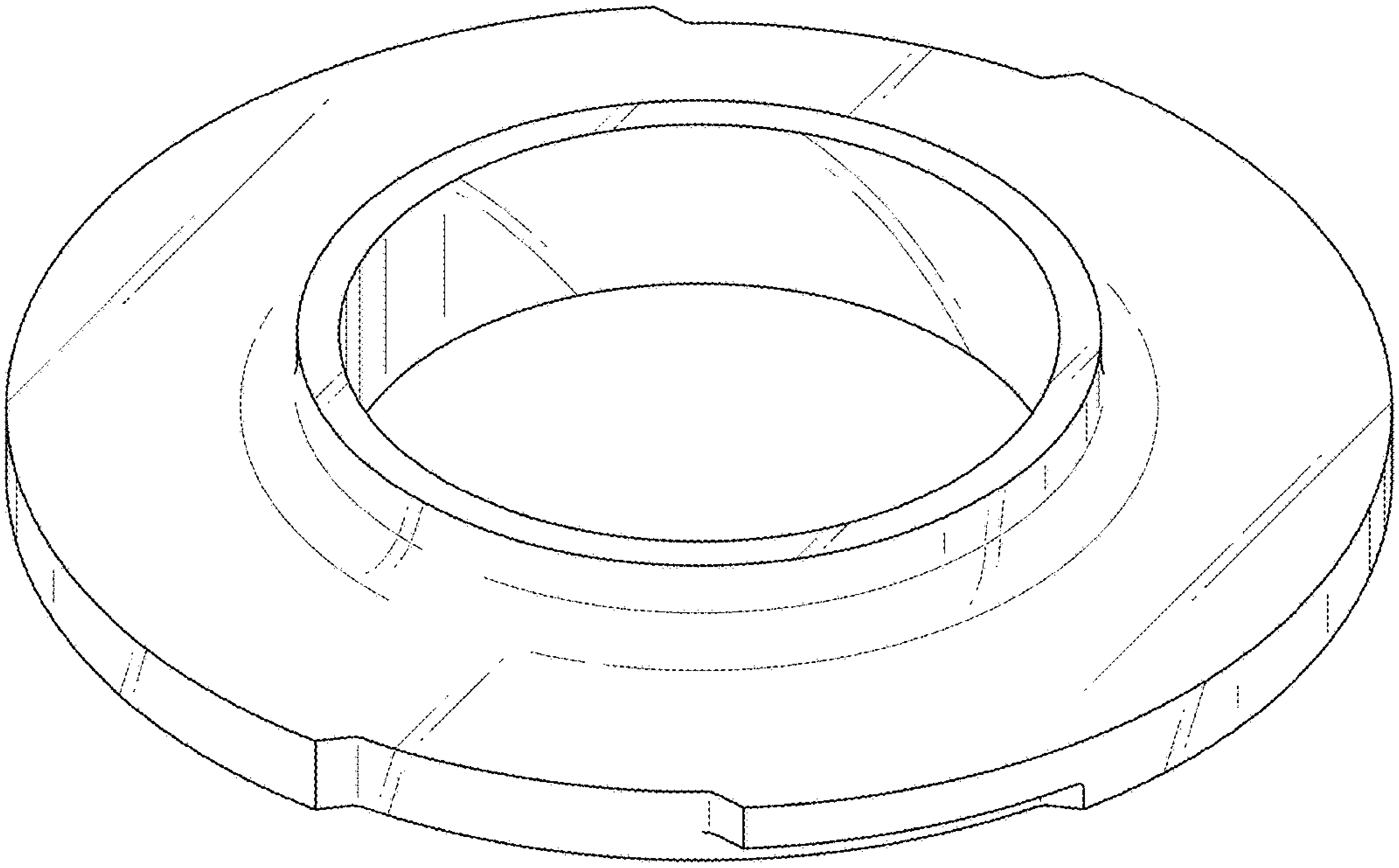

FIG. 1

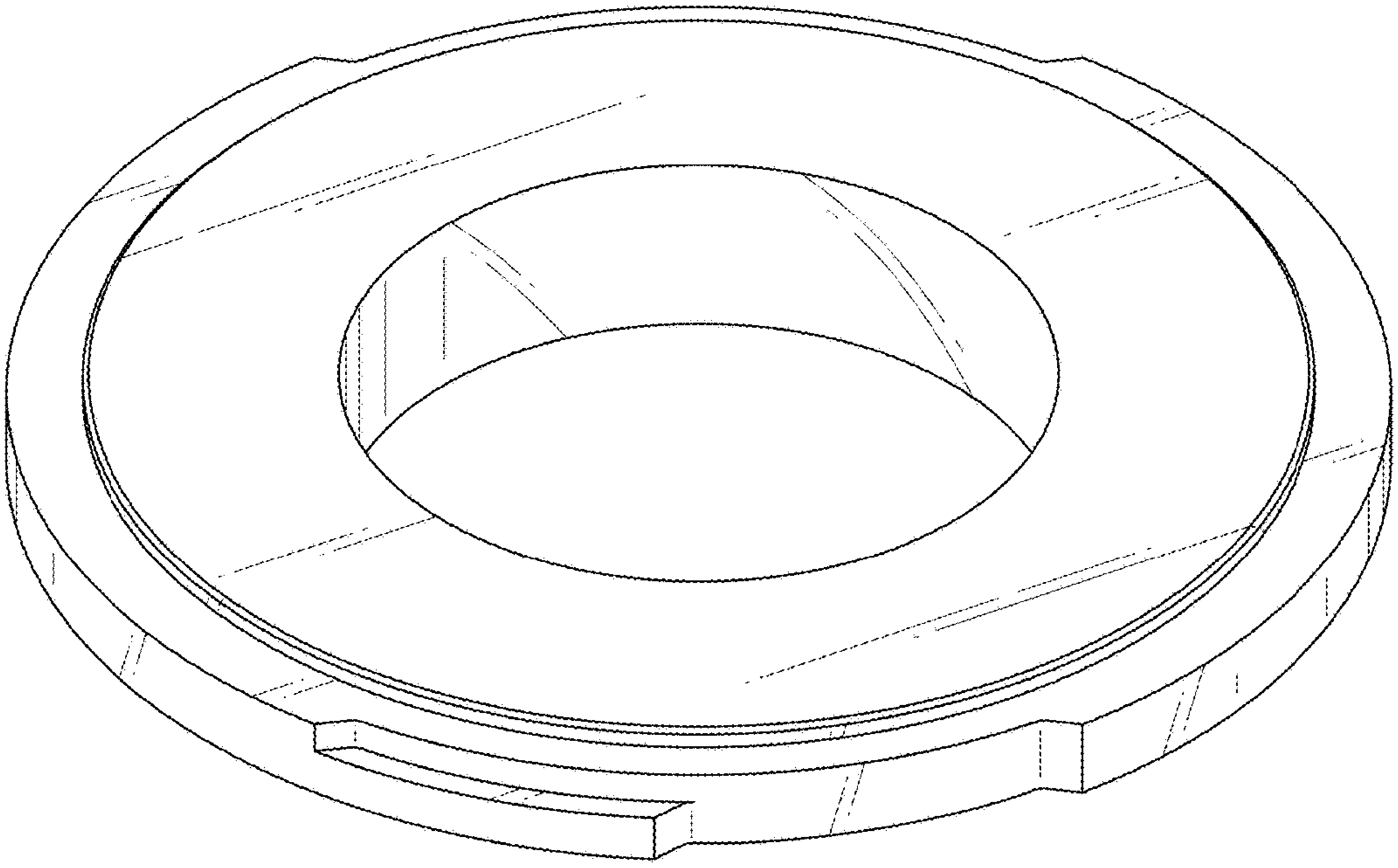

FIG. 2

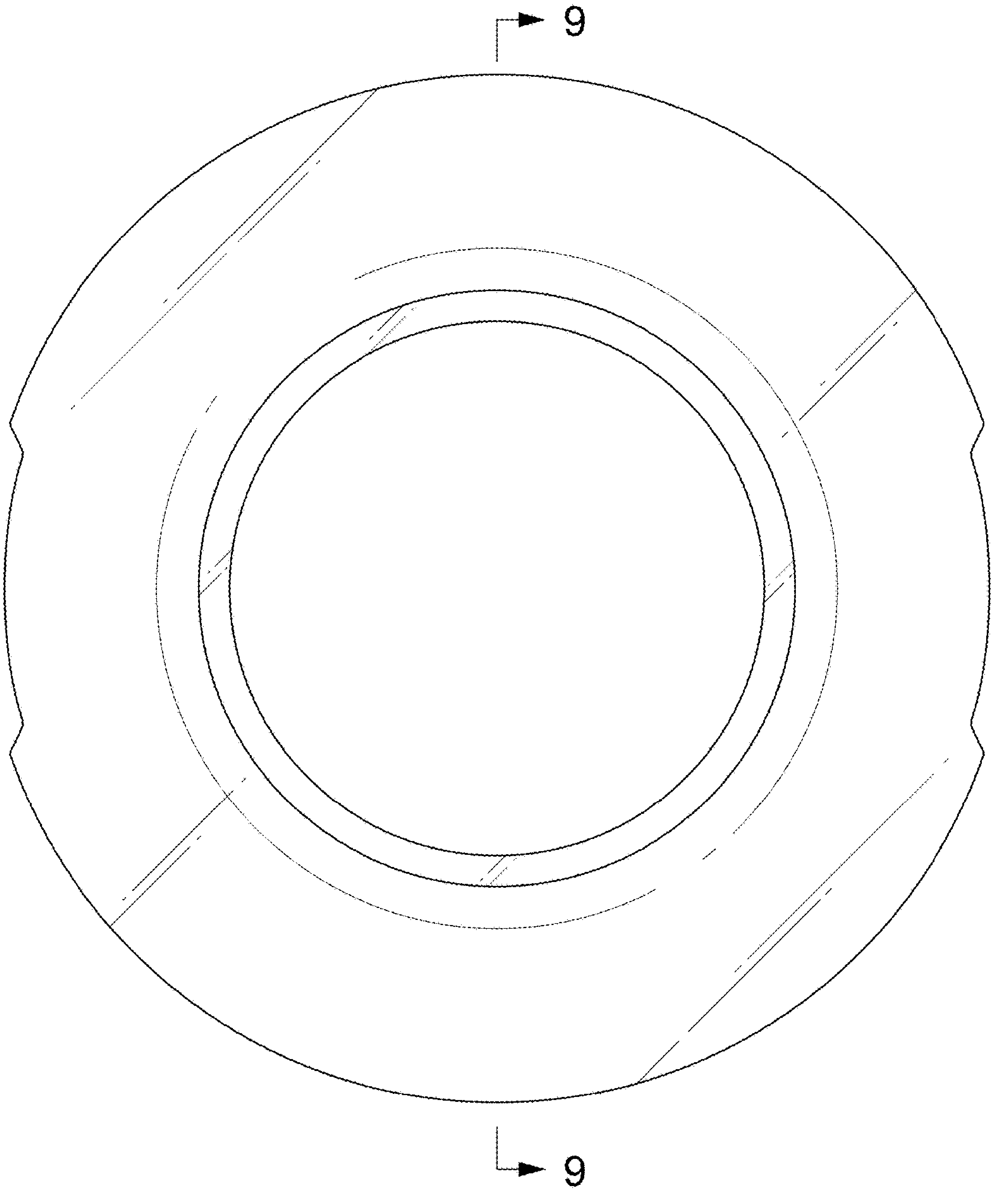

FIG. 3

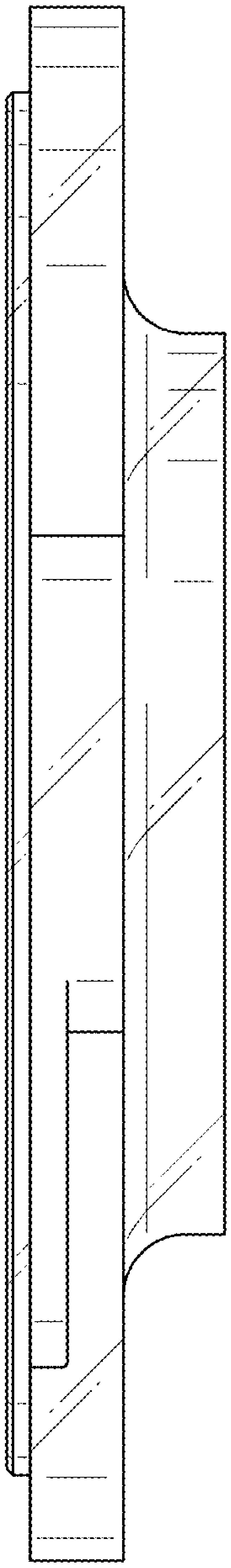

FIG. 4

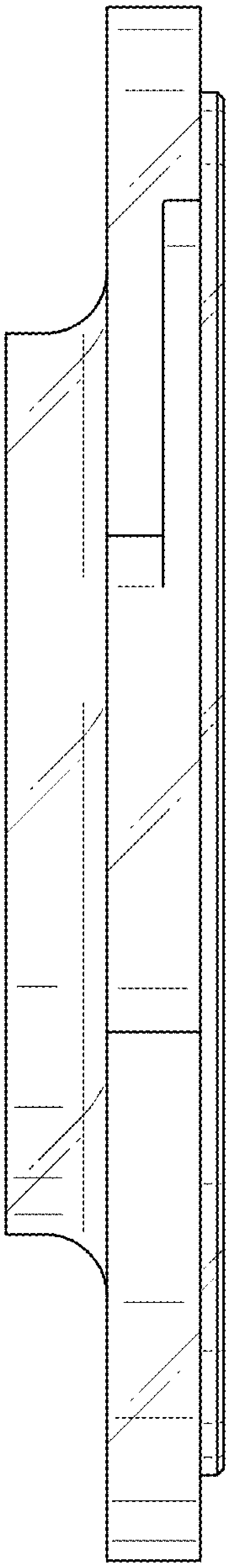

FIG. 5

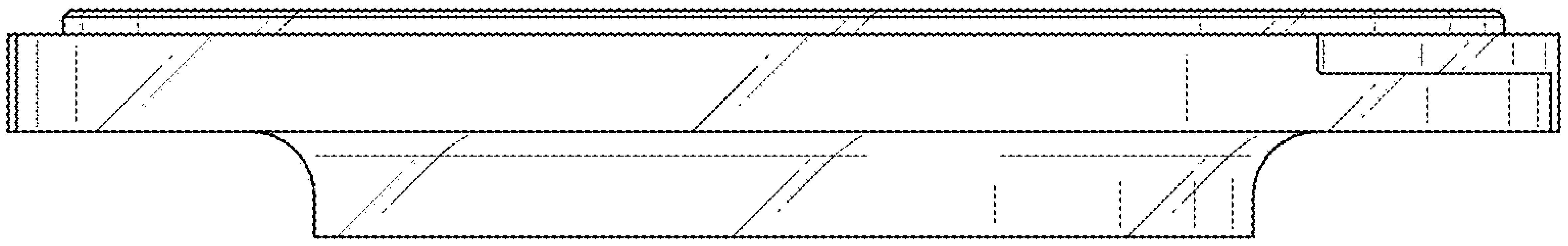

FIG. 6

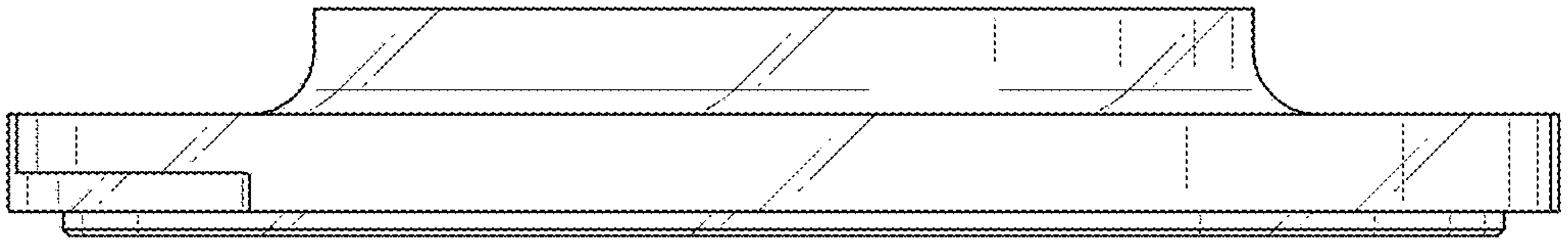

FIG. 7

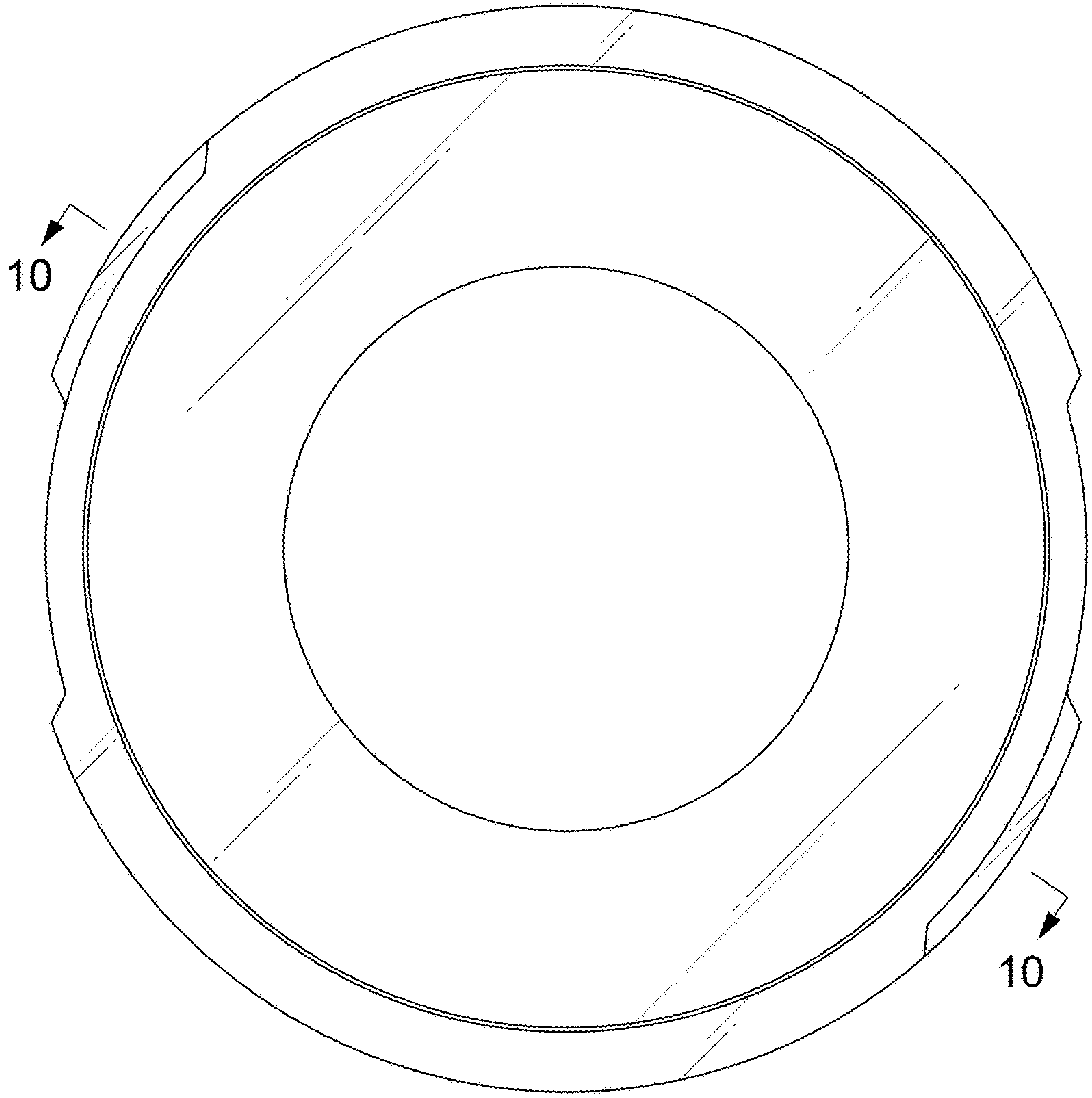

FIG. 8

FIG. 9

FIG. 10